

B1M160120HC

1200V ▲ 160mΩ ▲ 20A ▲ SiC MOSFET

SILICON CARBIDE SiC MOSFET ▲ THT type

N-channel enhancement mode

Low on-resistance and capacitance

TO-247-3L package ▲ Epoxy meets UL94-V0

Avalanche ruggedness

Especially for higher system efficiency

SPECIFICATION



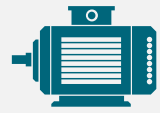




Item (T _c = 25°C, unless otherwise noted)		Characteristics
Operating Temperature Range	T _J	-55°C to +150°C
Storage Temperature Range	T _S	-55°C to +150°C
Drain-Source Voltage	V _{DS MAX}	1200V
Continuous Drain Current	I _D	20A
Drain-Source On-State Resistance ^{Note 1}	R _{DS(ON)TYP}	160mΩ
Reverse Transfer Capacitance ^{Note 2}	C _{RSS}	18pF
Power Dissipation	P _D	118W

Notes

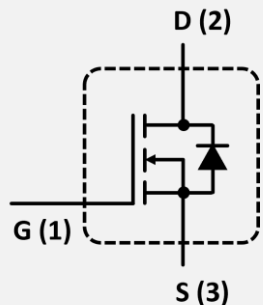
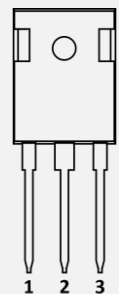
1: V_{GS} = 20V, I_D = 10A

2: V_{DS} = 800V, V_{GS} = 0V, f = 1MHz, V_{AC} = 25mV

APPLICATIONS

EV Charging	Industrial Inverters	Motors & Drives	Power Factor Correction	Renewable Energy	SMPS	UPS
						

PIN DESCRIPTION

Circuit Diagram	Outline - Front View	Pin No.	Symbol	Description
		1 2 3	G D S	Gate Drain Source

ABSOLUT MAXIMUM RATINGS ▲ $T_C = 25^\circ\text{C}$, unless otherwise noted

Item	Condition	Symbol		Unit
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_{DS} = 100\mu\text{A}$	$V_{DS\text{ MAX}}$	1200	V
Continuous Drain Current	$V_{GS} = 20\text{V}, T_C = 25^\circ\text{C}$	I_D	20	A
Continuous Drain Current	$V_{GS} = 20\text{V}, T_C = 100^\circ\text{C}$	I_D	13	A
Pulse Drain Current	Pulse with t_p limited by $T_{J\text{ MAX}}$	$I_{D, \text{ pulse}}$	40	A
Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	118	W
Gate Source Voltage		$V_{GS, \text{ MAX}}$	-10/+25	V
Recommended Gate Source Voltage		$V_{GS, \text{ op}}$	-5/+20	V
Operating Junction Temperature		T_J	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature		T_J	-55 to +150	$^\circ\text{C}$

ELECTRICAL CHARACTERISTICS ▲ $T_J = 25^\circ\text{C}$, unless otherwise noted

Item	Condition	Symbol	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 100\mu\text{A}$	$V_{(BR)DSS}$	1200			V
Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5\text{mA}$	$V_{GS(th)}$		2.7		V
Gate-Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.5\text{mA}, T_J = 150^\circ\text{C}$	$V_{GS(th)}$		2.1		V
Zero Gate Voltage Drain Current	$V_{DS} = 1200\text{V}, V_{GS} = 0\text{V}$	I_{DSS}		0.7	45	μA
Zero Gate Voltage Drain Current	$V_{DS} = 1200\text{V}, V_{GS} = 0\text{V}, T_J = 150^\circ\text{C}$	I_{DSS}		5	200	μA
Gate-Source Leakage Current	$V_{GS} = 20\text{V}, V_{DS} = 0\text{V}$	I_{GSS}			250	nA
Drain-Source On-State Resistance	$V_{GS} = 20\text{V}, I_D = 10\text{A}$	$R_{DS(ON)}$		160		m Ω
Drain-Source On-State Resistance	$V_{GS} = 20\text{V}, I_D = 10\text{A}, T_J = 150^\circ\text{C}$	$R_{DS(ON)}$		244		m Ω

Item	Condition	Symbol	Min.	Typ.	Max.	Unit
Dynamic Characteristics						
Input Capacitance	$V_{DS} = 800\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}, V_{AC} = 25\text{mV}$	C_{ISS}		1100		pF
Output Capacitance	$V_{DS} = 800\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}, V_{AC} = 25\text{mV}$	C_{OSS}		73		pF
Reverse Transfer Capacitance	$V_{DS} = 800\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}, V_{AC} = 25\text{mV}$	C_{RSS}		18		pF
Internal Gate Resistance	$f = 1\text{MHz}, V_{AC} = 25\text{mV}$	$R_{G(INT.)}$		2.8		Ω
Turn-On Delay Time	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}, R_{G(ext)} = 2.2\Omega, \text{ Inductive Load}$	$t_{D(ON)}$		15		ns
Rise Time	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}, R_{G(ext)} = 2.2\Omega, \text{ Inductive Load}$	t_R		19		ns
Turn-Off Delay Time	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}, R_{G(ext)} = 2.2\Omega, \text{ Inductive Load}$	$t_{D(OFF)}$		20		ns
Fall Time	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}, R_{G(ext)} = 2.2\Omega, \text{ Inductive Load}$	t_F		22		ns
Turn-on Switching Energy	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}, R_{G(ext)} = 2.2\Omega, \text{ Inductive Load}$	E_{ON}		63		μJ
Turn-off Switching Energy	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}, R_{G(ext)} = 2.2\Omega, \text{ Inductive Load}$	E_{OFF}		72		μJ

BUILT-IN SiC DIODE CHARACTERISTICS ▲ $T_J = 25^\circ\text{C}$, unless otherwise noted

Item	Condition	Symbol	Min.	Typ.	Max.	Unit
Source-Drain Diode						
Inverse Diode Forward Voltage	$V_{GS} = -5\text{V}, I_{SD} = 5\text{A}$	V_{SD}		5.1		V
Reverse Recovery Charge	$V_{GS} = 5\text{V}, I_{SD} = 10\text{A}, V_{DS} = 800\text{V},$ $di/dt = 400\text{A}/\mu\text{s}$	Q_{RR}		82		nC
Peak Reverse Recovery Current	$V_{GS} = 5\text{V}, I_{SD} = 10\text{A}, V_{DS} = 800\text{V},$ $di/dt = 400\text{A}/\mu\text{s}$	I_{RRM}		2.45		A

GATE CHARGE CHARACTERISTICS ▲ $T_J = 25^\circ\text{C}$, unless otherwise noted

Item	Condition	Symbol	Min.	Typ.	Max.	Unit
Gate to Source Charge	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}$	Q_{GS}		12		nC
Gate to Drain Charge	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}$	Q_{GD}		31		nC
Total Gate Charge	$V_{DS} = 800\text{V}, V_{GS} = -5/+20\text{V}, I_D = 10\text{A}$	Q_G		60		nC

THERMAL RESISTANCE PERFORMANCE

Item	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$		1.085		K/W

REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 1 • Forward Output Characteristics I_{DS} vs. V_{DS} ,
 $T_J = 25^\circ\text{C}$

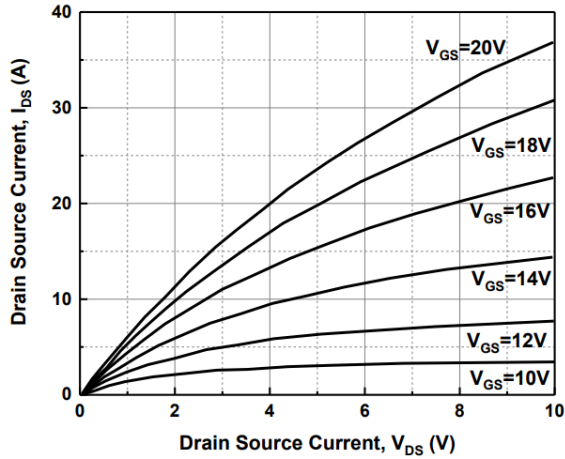


Fig. 2 • Forward Output Characteristics I_{DS} vs. V_{DS} ,
 $T_C = 150^\circ\text{C}$

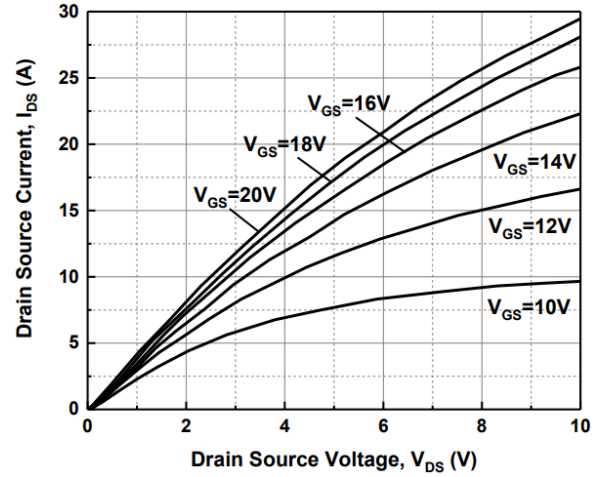


Fig. 3 • Transfer Characteristics for various
Junction Temperature T_J

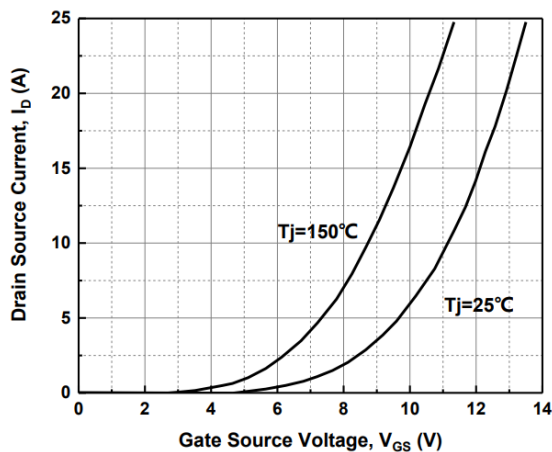


Fig. 4 • On-Resistance R_{ON} vs. Gate Voltage V_{GS}
for various Junction Temperature T_J

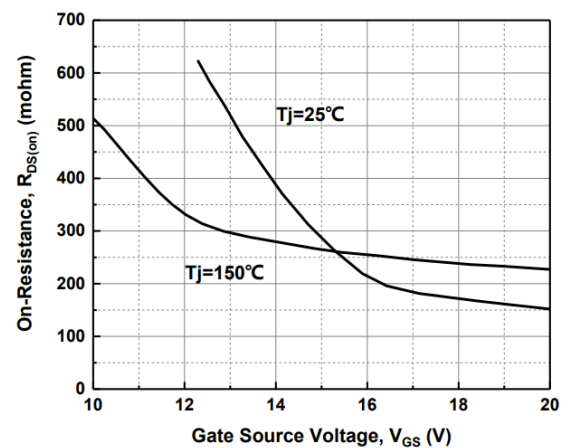


Fig. 5 • On-Resistance R_{ON} vs. Junction Temperature T_J
at $V_{GS} = 20\text{V}$, $I_{DS} = 10\text{A}$

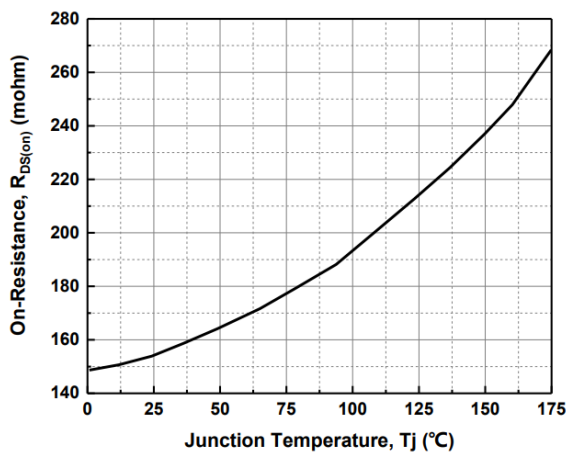
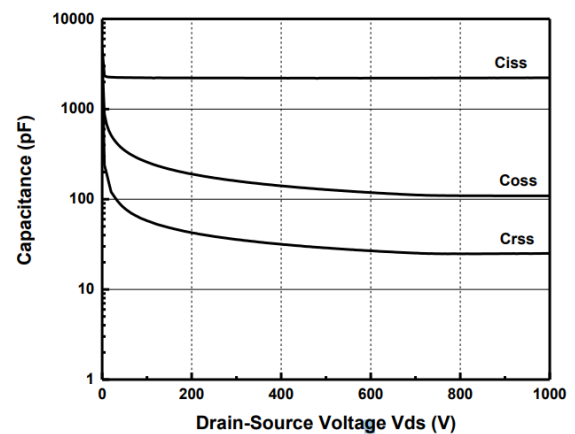


Fig. 6 • Capacitances vs. Drain to Source Voltage V_{DS}
(0 to 1000V)



REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 7 • Continuous Drain Current Derating I_{DS} vs. Case Temperature T_C

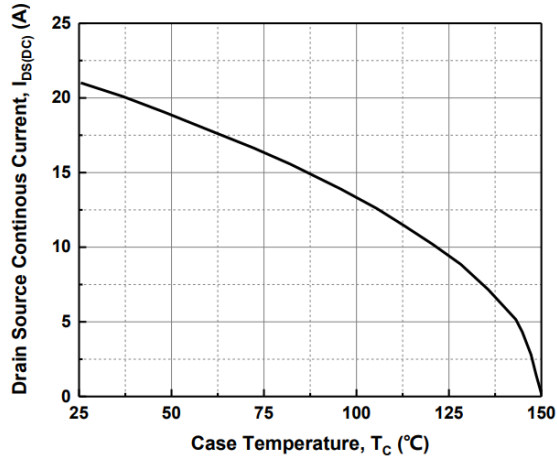


Fig. 8 • Maximum Power Dissipation Derating P_D vs. Case Temperature T_C

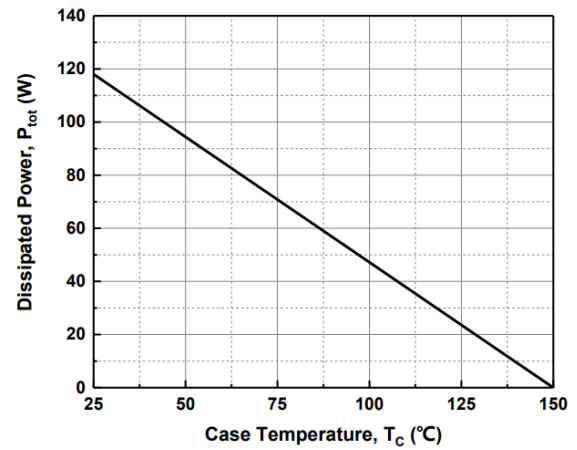


Fig. 9 • Transient Thermal Impedance (Junction – Case)

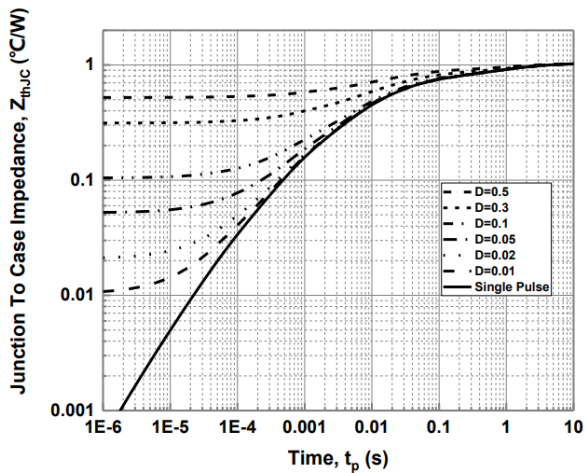
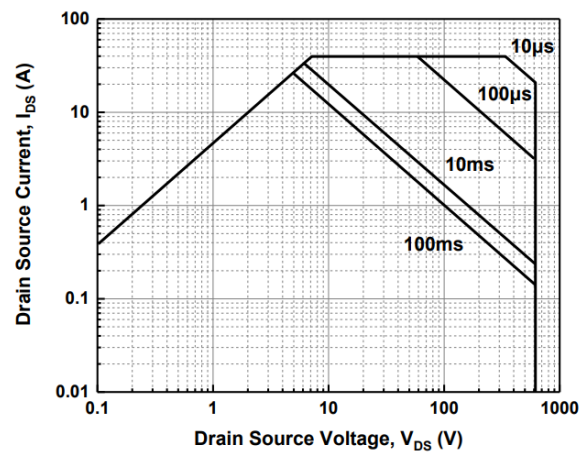
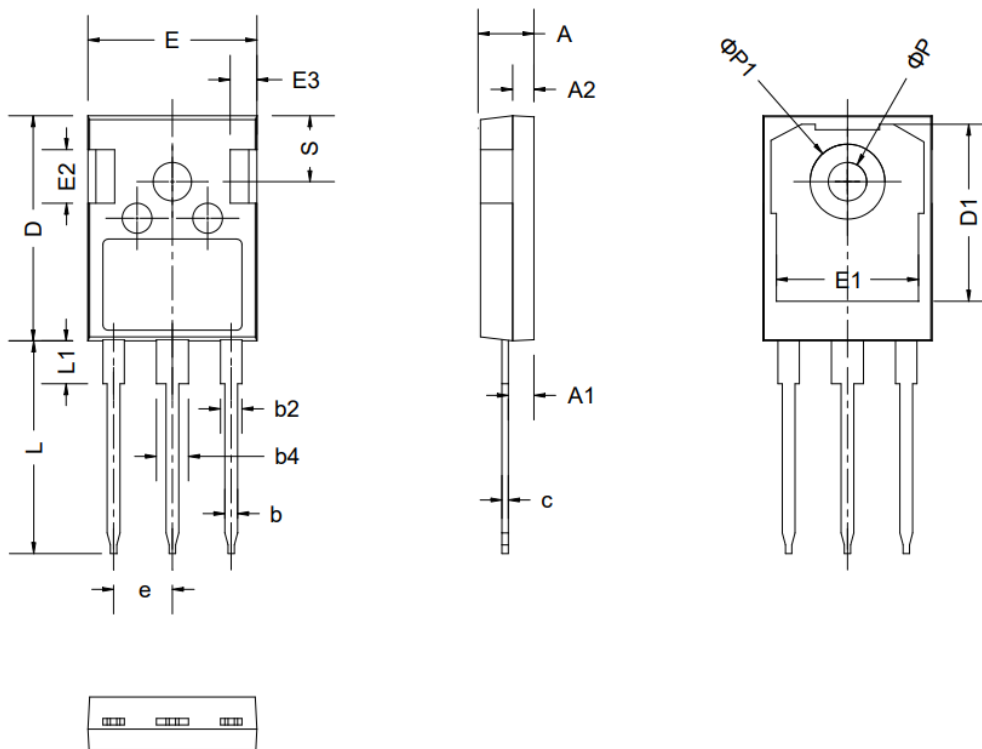


Fig. 10 • Safe Operating Area



PACKAGE OUTLINE



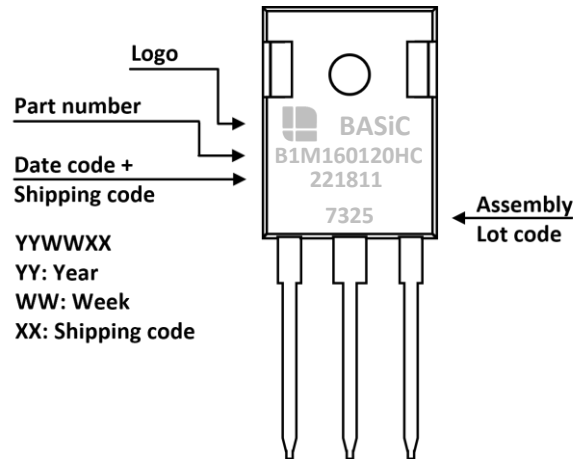
Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44 BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
ØP	3.40	3.60	3.80
ØP1	-	-	7.30
S	6.16 BSC		

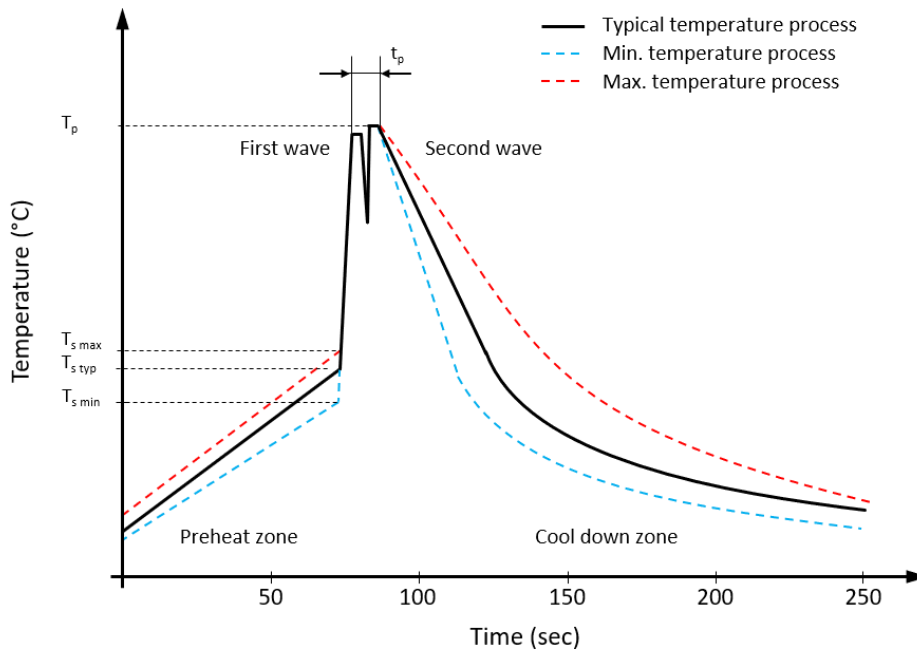
ORDERING INFORMATION

Part Number	Package	Packing	Tube Qty.	Inner Box Qty.	Outer Box Qty.
B1M160120HC	TO-247-3L	Tube	30pcs	300pcs	1,800pcs

PART MARKING



RECOMMENDED WAVE SOLDERING PROFILE ▲ THT PACKAGE



Classification wave soldering profile ▲ Refer to EN 61760-1: 2006

Profile Features		Value ▲ Sn-Pb Assembly	Value ▲ Pb-free Assembly
Preheat temperature min.	$T_{s\ min}$	100 °C	100 °C
Preheat temperature typical	$T_{s\ typ}$	120 °C	120 °C
Preheat temperature max.	$T_{s\ max}$	130 °C	130 °C
Preheat time t_s from $T_{s\ min}$ to $T_{s\ max}$	t_s	70 seconds	70 seconds
Peak temperature	T_p	235 °C to 260 °C	245 °C to 260 °C
Time of actual peak temperature	t_p	Max. 10 seconds Max. 5 second each wave	Max. 10 seconds Max. 5 second each wave
Ramp-down date min.		~ 2 °C/second	~ 2 °C/second
Ramp-down rate typical		~ 3.5 °C/second	~ 3.5 °C/second
Ramp-down rate max.		~ 5 °C/second	~ 5 °C/second

REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

DISCLAIMER

Except for the written expressed warranties, MGT does not implicitly, by assumption or whatever else, warrant, under-take, promise any other warranty or guaranty for any MGT product.

All information and technical specifications made available by MGT are for guidance only and we reserve the right to change or modify them without prior notice. Unless expressly stated in writing by MGT, we reject any guarantees, obligations, or warranties.

All MGT products with the technical specifications described are suitable for use in certain applications. Operating, production, storage and environmental conditions can have a massive influence on the parameters mentioned in the data sheets, which cause the performance to vary over time.

It is subject to the user's duty of care to design and validate his products in such a way that appropriate measures are taken, such as protective circuits or redundant systems to ensure the safety standards required in the application.

MGT components are not designed or rated for use in life support, rescue, safety critical, military, or aerospace applications where failure or malfunction could result in property or environmental damage, serious injury or death. In the aforementioned cases, please contact us before using MGT products.

In principle, we reserve all rights and MGT's general terms and conditions apply. You can find them on our website www.mgt.co.com.